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CAU 2813



Express Mail No. EV335856560US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Fukutomi et al.

Confirmation No.: 9036

Serial No.: 10/042,408

Art Unit: 2813

Filed: January 8, 2002

Examiner: Nema O. Berezny

For: FABRICATION PROCESS OF
SEMICONDUCTOR PACKAGE
AND SEMICONDUCTOR
PACKAGE

Attorney Docket No.: 7426-08

RECEIVED
AUG 21 2003
TECHNOLOGY CENTER 2800

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450 Sir:

In accordance with the duty of disclosure provisions of 37 C.F.R. §1.56, there is hereby provided certain information which the Examiner may consider material to the examination of the subject U.S. patent application. It is requested that the Examiner make this information of record if it is deemed material to the examination of the application.

Enclosures accompanying this Information Disclosure Statement are a list of all patents, publications, applications, or other information submitted for consideration by the office and a legible copy of each publication or that portion which caused it to be listed on the PTO-1449;

This Information Disclosure Statement is filed under C.F.R. § 1.97(b) and is filed before the mailing of the First Office Action on its merits.

This application is a continuation application under 37 C.F.R. §1.60 or §1.53(b) or (d). Copies of publications listed on Form PTO-1449 from prior application Serial No. 09/487,682, filed on January 19, 2000 and prior application Serial No. 09/326,316, filed on June 7, 1999, of which this application claims priority under 35 U.S.C. §120, are submitted herewith

The Commissioner is authorized to charge any additional fee required or credit any overpayment for this Information Disclosure Statement and/or Petition to Pennie & Edmonds LLP Deposit Account No. 16-1150.

No admission is made that the information cited in this Statement is, or is considered to be, material to patentability nor a representation that a search has been made (other than a search report of a foreign counterpart application or PCT International Search Report if submitted herewith). 37 C.F.R. §§1.97(g) and (h).

Respectfully submitted,

Date: August 18, 2003

31,636

James G. Markey

(Reg. No.)

By: Steven K. Fukuda (Reg. No. 44,690)

PENNIE & EDMONDS LLP

1155 Avenue of the Americas

New York, NY 10036

(212) 790-9090



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Application of: Fukutomi et al. Confirmation No.: 9036
Serial No.: 10/042,408 Art Unit: 2813
Filed: January 8, 2002 Examiner: Nema O. Berezny
For: FABRICATION PROCESS OF SEMICONDUCTOR PACKAGE AND SEMICONDUCTOR PACKAGE Attorney Docket No.: 7426-082

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450 Sir:

In accordance with the duty of disclosure provisions of 37 C.F.R. §1.56, there is hereby provided certain information which the Examiner may consider material to the examination of the subject U.S. patent application. It is requested that the Examiner make this information of record if it is deemed material to the examination of the application.

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Respectfully submitted,

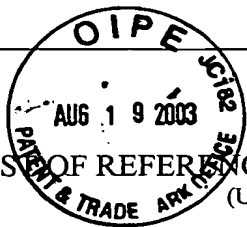
Date: August 18, 2003

James G. Markey

By: Steven K. Fukuda (Reg. No. 44,690)
PENNIE & EDMONDS LLP
1155 Avenue of the Americas
New York, NY 10036
(212) 790-9090

31,636
(Reg. No.)

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LIST OF REFERENCES CITED BY APPLICANT

(Use several sheets if necessary)

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APPLICATION NO

10/042,408

APPLICANT

Fukutomi *et al.*

FILING DATE

January 8, 2002

GROUP

2813

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	A28	4,975,765	12/04/1990	Ackermann <i>et al.</i>			
	A29	5,173,766	12/22/1992	Long <i>et al.</i>			
	A30	5,399,903	03/21/1995	Rostoker <i>et al.</i>			

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	A31	WO 90/13991	11/15/1990	PCT/US90/01828				

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

	A32	Tummala <i>et al.</i> ; Microelectronics Packaging Handbook: Semiconductor Packaging Second Edition Part II

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.